



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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企业微信二维码



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Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D Max T _C = +25°C
80V	6.9mΩ @ V _{GS} = 10V	70A
	10.4mΩ @ V _{GS} = 4.5V	57A

Description

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power-management applications.

Applications

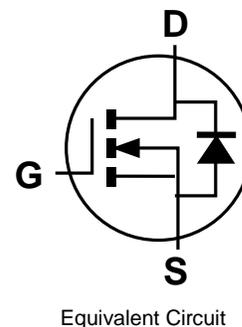
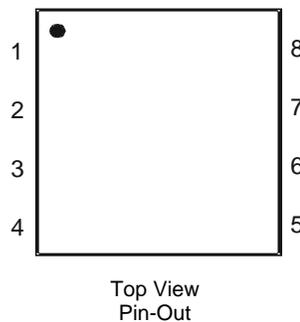
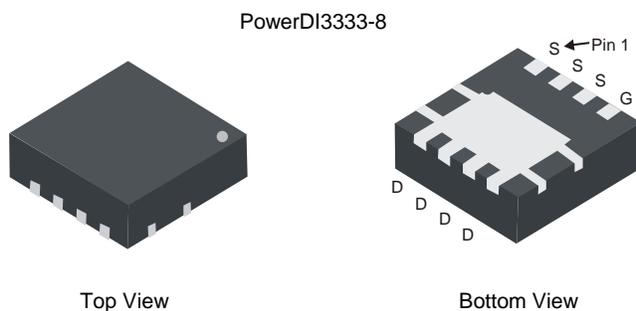
- Backlighting
- Power-management functions
- DC-DC converters

Features and Benefits

- Rated to +175°C – Ideal for High Ambient Temperature Environments
- Low R_{DS(ON)} – Ensures On-State Losses are Minimized
- Excellent Q_{gd} × R_{DS(ON)} Product (FOM)
- Advanced Technology for DC-DC Converters
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies Just 33% of the Board Area Occupied by SO-8 Enabling Smaller End Product
- 100% Unclamped Inductive Switching (UIS) Test in Production – Ensures More Reliable and Robust End Application

Mechanical Data

- Package: PowerDI[®]3333-8
- Package Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminal Finish – Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 
- Weight: 0.034 grams (Approximate)



Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	80	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current (Note 7) $V_{GS} = 10\text{V}$	I_D	$T_C = +25^\circ\text{C}$	70
		$T_C = +100^\circ\text{C}$	49
Continuous Drain Current (Note 6) $V_{GS} = 10\text{V}$	I_D	$T_A = +25^\circ\text{C}$	17
		$T_A = +100^\circ\text{C}$	12
Maximum Continuous Body Diode Forward Current (Note 6)	I_S	17	A
Pulsed Drain Current (10 μs Pulse, Duty Cycle = 1%)	I_{DM}	280	A
Pulsed Body Diode Forward Current (10 μs Pulse, Duty Cycle = 1%)	I_{SM}	280	A
Avalanche Current, $L = 1\text{mH}$ (Note 8)	I_{AS}	18	A
Avalanche Energy, $L = 1\text{mH}$ (Note 8)	E_{AS}	162	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 5)	P_D	1.2	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	124	$^\circ\text{C/W}$
Total Power Dissipation (Note 6)	P_D	2.8	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	53	$^\circ\text{C/W}$
Total Power Dissipation (Note 7)	P_D	50	W
Thermal Resistance, Junction to Case (Note 7)	$R_{\theta JC}$	3	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +175	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 9)						
Drain-Source Breakdown Voltage	BV_{DSS}	80	—	—	V	$V_{GS} = 0\text{V}, I_D = 1\text{mA}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 64\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 9)						
Gate Threshold Voltage	$V_{GS(TH)}$	1.2	—	2.5	V	$V_{DS} = V_{GS}, I_D = 1\text{mA}$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	—	5.3	6.9	m Ω	$V_{GS} = 10\text{V}, I_D = 20\text{A}$
		—	7.9	10.4		$V_{GS} = 4.5\text{V}, I_D = 10\text{A}$
Diode Forward Voltage	V_{SD}	—	0.8	1.2	V	$V_{GS} = 0\text{V}, I_S = 20\text{A}$
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C_{ISS}	—	2254	—	pF	$V_{DS} = 40\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Output Capacitance	C_{OSS}	—	745	—		
Reverse Transfer Capacitance	C_{RSS}	—	31	—		
Gate Resistance	R_g	—	1.98	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$
Total Gate Charge ($V_{GS} = 4.5\text{V}$)	Q_g	—	18.3	—	nC	$V_{DS} = 40\text{V}, I_D = 14\text{A}$
Total Gate Charge ($V_{GS} = 10\text{V}$)	Q_g	—	37.7	—		
Gate-Source Charge	Q_{gs}	—	5.3	—		
Gate-Drain Charge	Q_{gd}	—	7.8	—		
Turn-On Delay Time	$t_{D(ON)}$	—	6.9	—	ns	$V_{DD} = 40\text{V}, V_{GS} = 10\text{V}, I_D = 14\text{A}, R_G = 6\Omega$
Turn-On Rise Time	t_r	—	12	—		
Turn-Off Delay Time	$t_{D(OFF)}$	—	37	—		
Turn-Off Fall Time	t_f	—	21	—		
Body Diode Reverse Recovery Time	t_{RR}	—	42	—	ns	$I_S = 14\text{A}, di/dt = 100\text{A}/\mu\text{s}$
Body Diode Reverse Recovery Charge	Q_{RR}	—	53	—	nC	

- Notes:
- Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
 - Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 - Thermal resistance from junction to soldering point (on the exposed drain pad).
 - I_{AS} and E_{AS} ratings are based on low frequency and duty cycles to keep $T_J = +25^\circ\text{C}$.
 - Short duration pulse test used to minimize self-heating effect.
 - Guaranteed by design. Not subject to product testing.

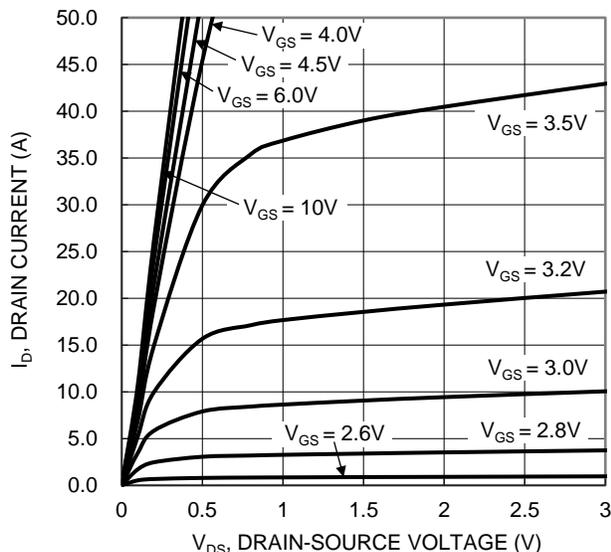


Figure 1. Typical Output Characteristic

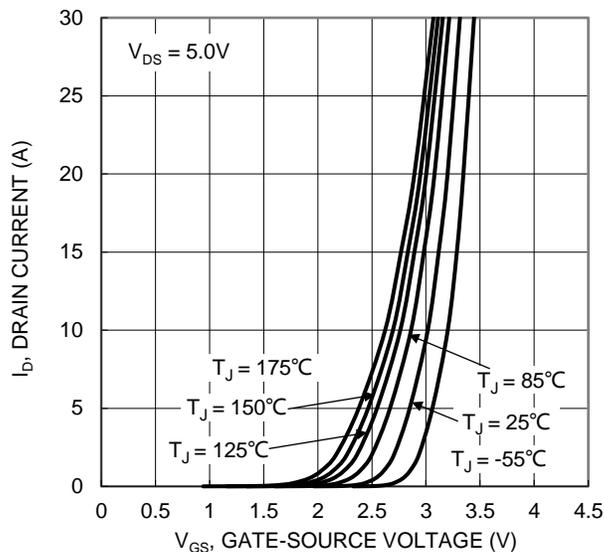


Figure 2. Typical Transfer Characteristic

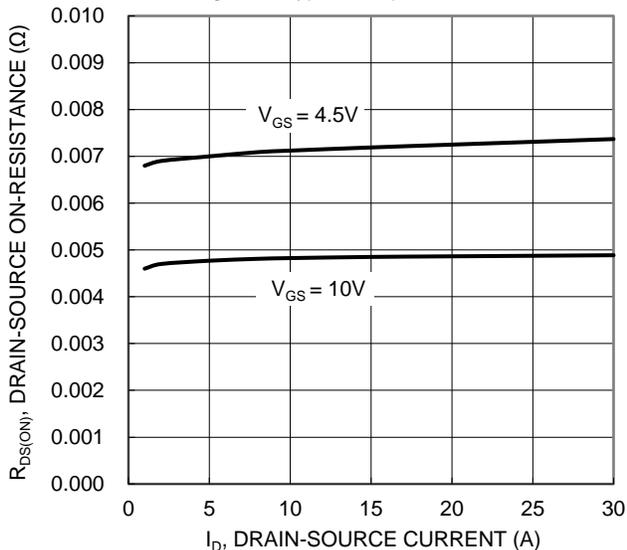


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

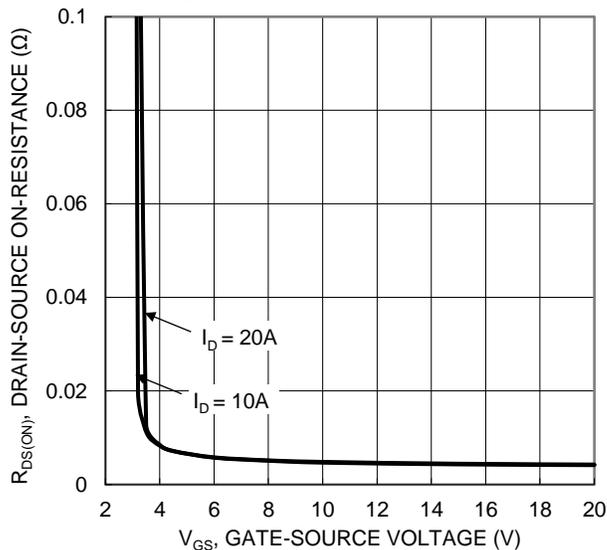


Figure 4. Typical Transfer Characteristic

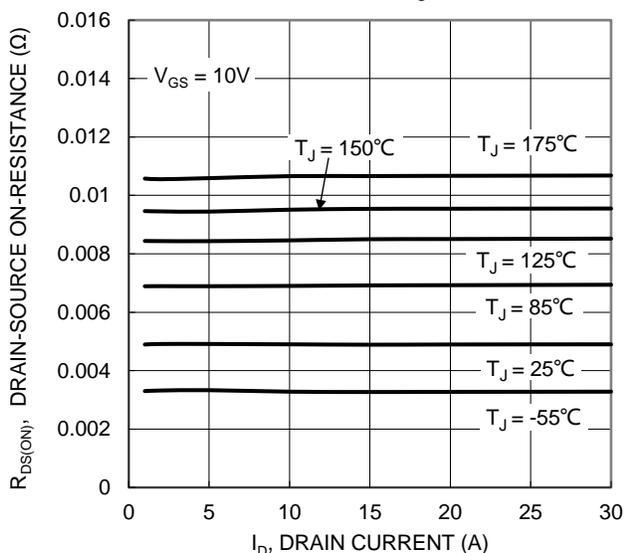


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

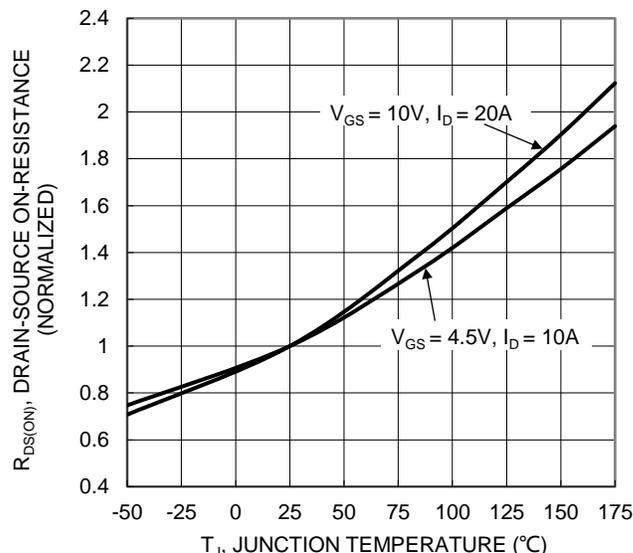


Figure 6. On-Resistance Variation with Temperature

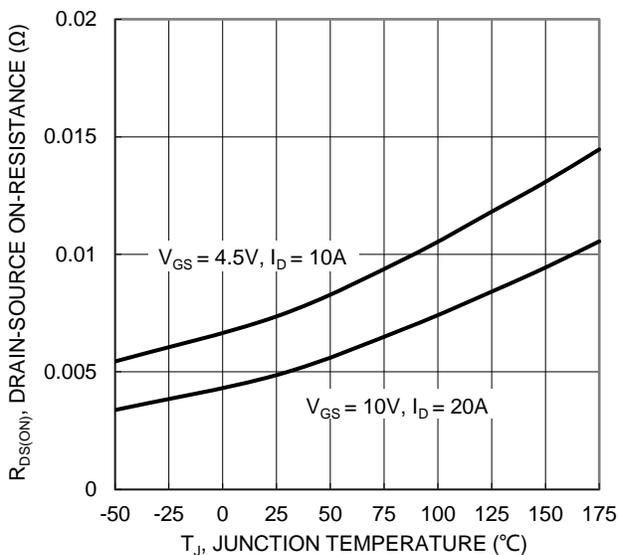


Figure 7. On-Resistance Variation with Temperature

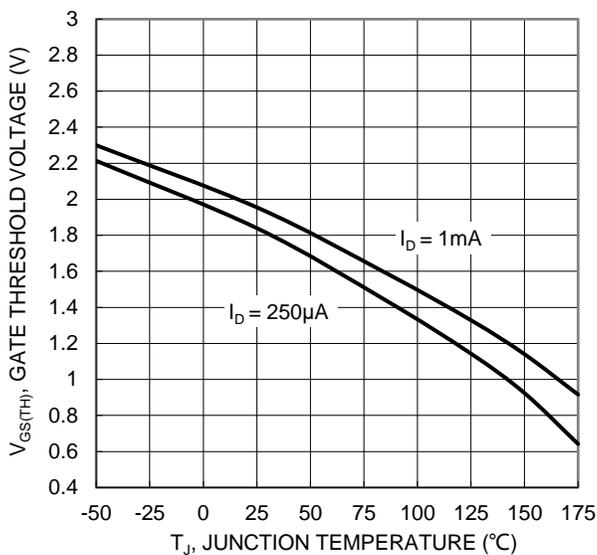


Figure 8. Gate Threshold Variation vs. Junction Temperature

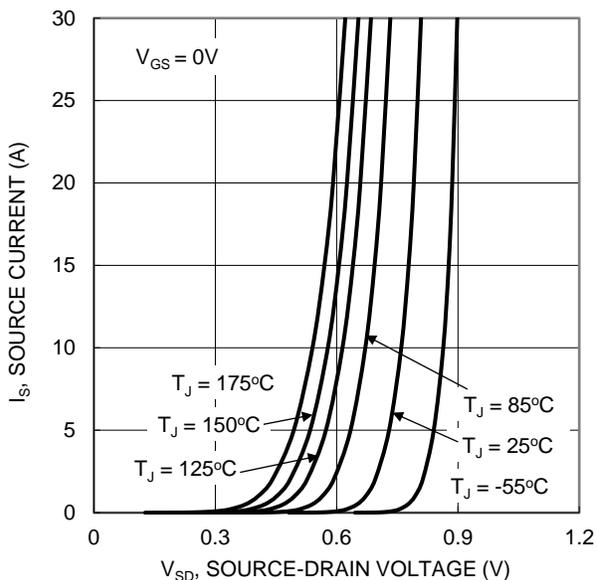


Figure 9. Diode Forward Voltage vs. Current

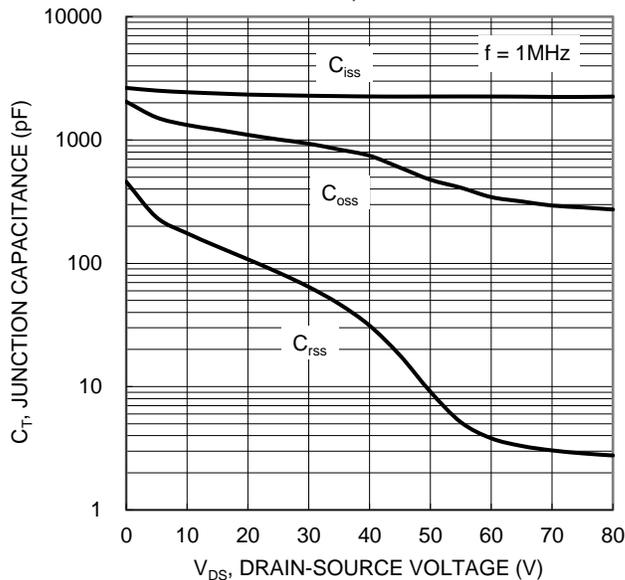


Figure 10. Typical Junction Capacitance

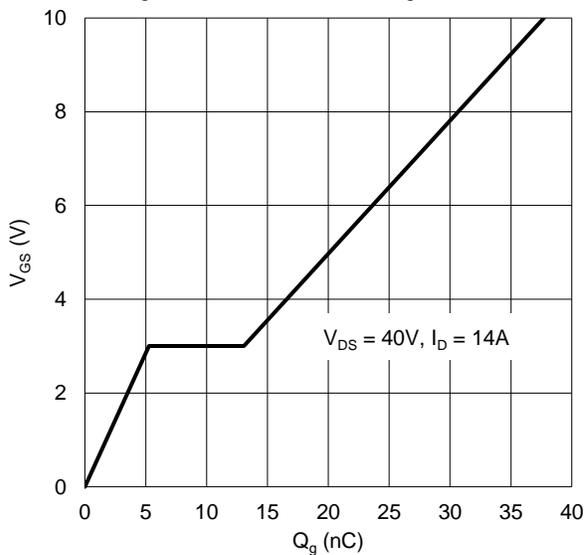


Figure 11. Gate Charge

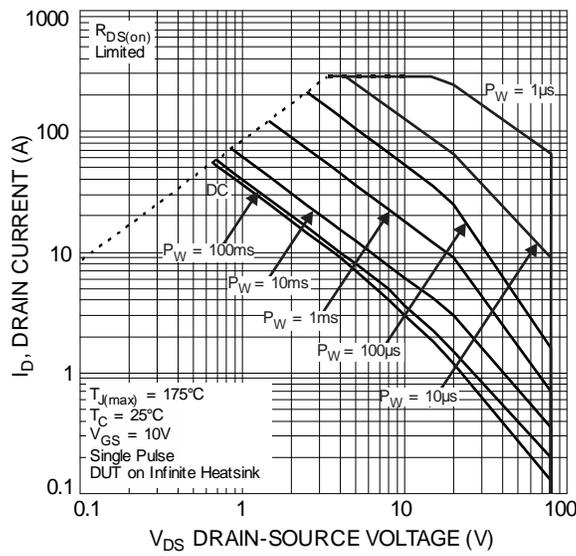
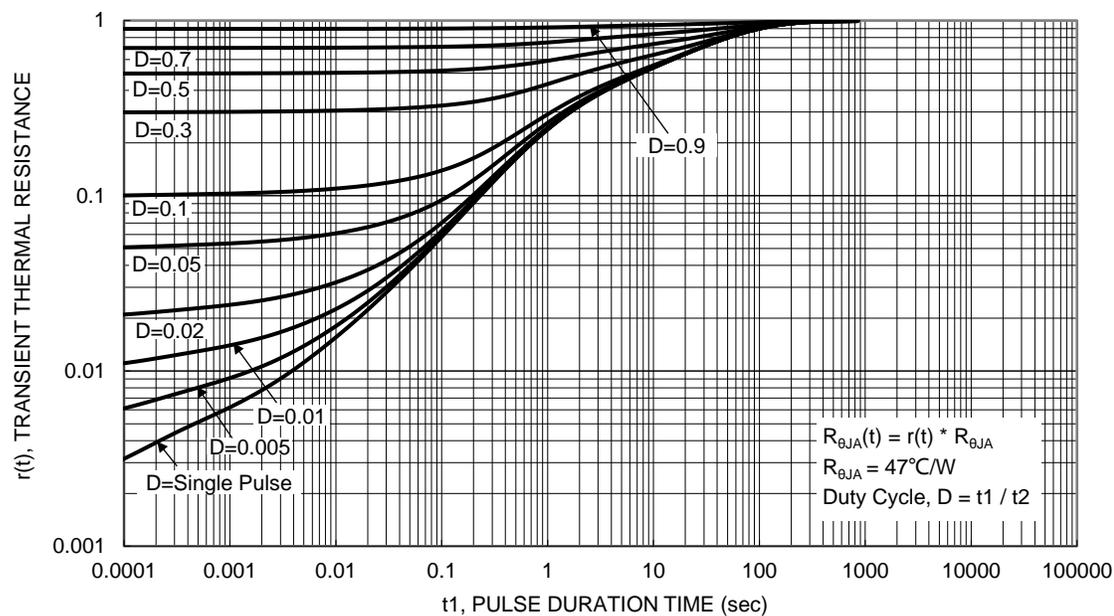
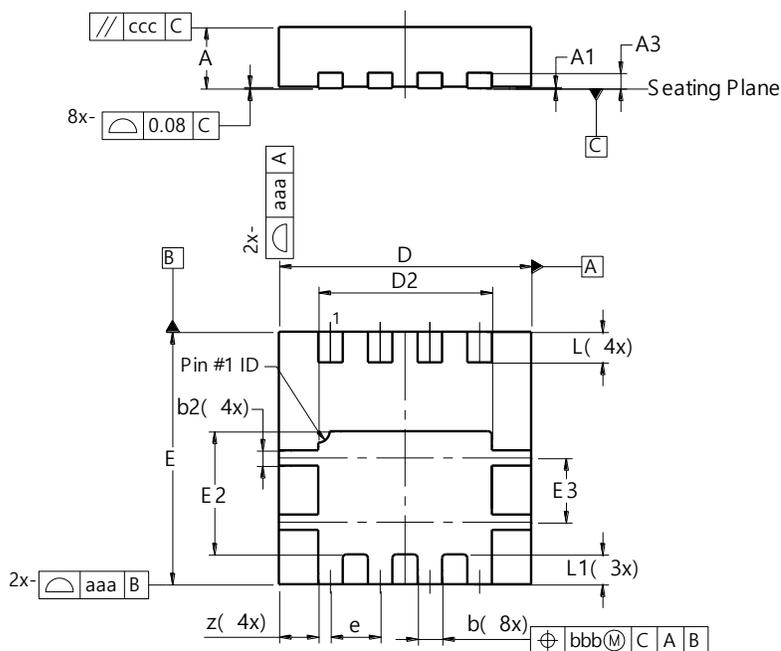


Figure 12 SOA, Safe Operation Area



Package Outline Dimensions

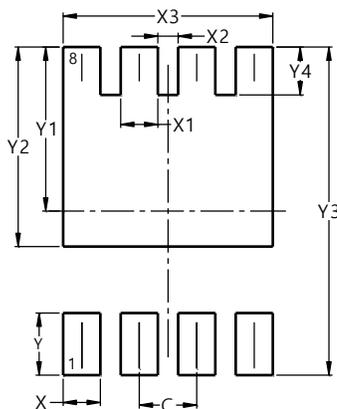
PowerDI3333-8



PowerDI3333-8			
Dim	Min	Max	Typ
A	0.75	0.85	0.80
A1	0.00	0.05	0.02
A3	-	-	0.203
b	0.27	0.37	0.32
b2	-	-	0.20
D	3.25	3.35	3.30
D2	2.22	2.32	2.27
E	3.25	3.35	3.30
E2	1.56	1.66	1.61
E3	0.79	0.89	0.84
e	-	-	0.65
L	0.35	0.45	0.40
L1	-	-	0.39
z	-	-	0.515
aaa	0.25		
bbb	0.10		
ccc	0.10		
All Dimensions in mm			

Suggested Pad Layout

PowerDI3333-8



Dimensions	Value (in mm)
C	0.650
X	0.420
X1	0.420
X2	0.230
X3	2.370
Y	0.700
Y1	1.850
Y2	2.250
Y3	3.700
Y4	0.540